

# RELIABILITY MONITOR

PRODUCT	MONITOR DATE	DATE CODE	ASSEMBLY FACILITY	ASSEMBLY LOT NO	PROCESS TYPE	PACKAGE TYPE
DS12887 (w/BR1225)	Jul-96	9627 A2	DALLAS	DA082313AAA	N/A	24 MODULE

**STRESS/JOB NO.**

**READPOINT  
(Sample Size/No. of Fails)**

Hi Temp Storage 85°C, No Bias P-17818	<u>48 Hr</u> 200/0	<u>Cum %</u> 0.0%
Temp Cycle 0°C to +70°C P-17874	<u>300 ~</u> <u>1K ~</u> 100/0   100/0	<u>Cum %</u> 0.0%
Biased Moisture 85°C/85% RH, 5.5 V. P-17875	<u>274 Hr</u> <u>959 Hr</u> 100/0   100/1 F1	<u>Cum %</u> 1.0%
	Phys. Dimen. <u>P-17817</u> 6/0	Solderability <u>P-17816</u> 24/0

**Failure Mode**

F1: Vbatt. Low

**Failure Analysis**

In process, 960291